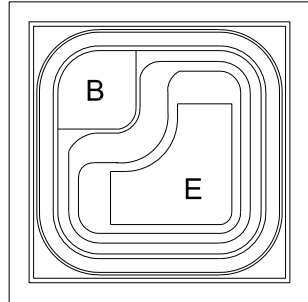


The CP388X-BCX70K is a silicon NPN transistor designed for low noise amplifier applications.



BACKSIDE COLLECTOR R0

**MECHANICAL SPECIFICATIONS:**

Die Size	13 x 13 MILS
Die Thickness	5.9 MILS
Base Bonding Pad Size	3.9 x 3.9 MILS
Emitter Bonding Pad Size	5.4 x 5.4 MILS
Top Side Metalization	Al-Si – 17,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	1.8 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	102,852

**MAXIMUM RATINGS:** ( $T_A=25^\circ\text{C}$ )

	SYMBOL		UNITS
Collector-Base Voltage	$V_{CBO}$	45	V
Collector-Emitter Voltage	$V_{CEO}$	45	V
Emitter-Base Voltage	$V_{EBO}$	5.0	V
Continuous Collector Current	$I_C$	100	mA
Peak Collector Current	$I_{CM}$	200	mA
Peak Base Current	$I_{BM}$	200	mA
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

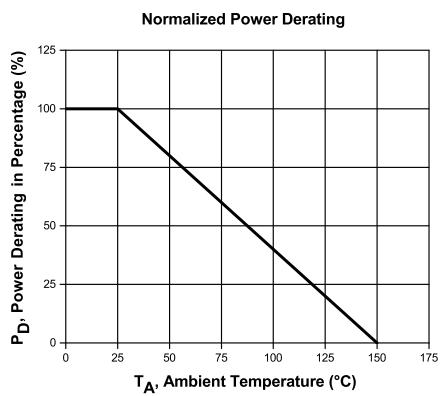
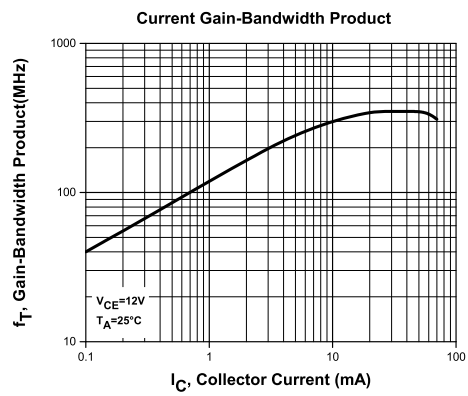
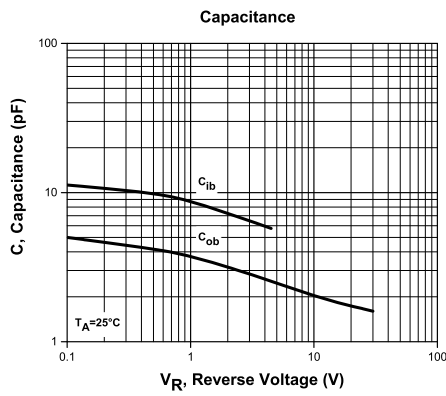
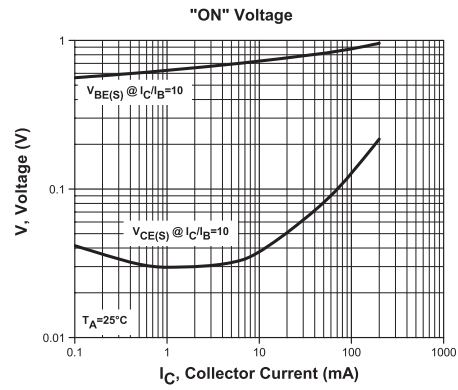
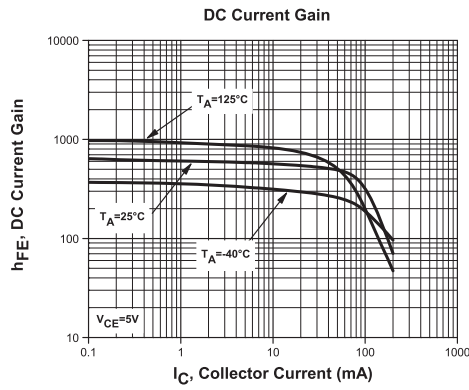
**ELECTRICAL CHARACTERISTICS:** ( $T_A=25^\circ\text{C}$ )

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
$I_{CBO}$	$V_{CB}=45\text{V}$			20	nA
$I_{EBO}$	$V_{EB}=4.0\text{V}$			20	nA
$BV_{CBO}$	$I_C=10\mu\text{A}$	45			V
$BV_{CEO}$	$I_C=10\text{mA}$	45			V
$BV_{EBO}$	$I_E=1.0\mu\text{A}$	5.0			V
$V_{CE(SAT)}$	$I_C=10\text{mA}, I_B=250\mu\text{A}$	0.05		0.35	V
$V_{CE(SAT)}$	$I_C=50\text{mA}, I_B=1.25\text{mA}$	0.10		0.55	V
$V_{BE(SAT)}$	$I_C=10\text{mA}, I_B=250\mu\text{A}$	0.60		0.85	V
$V_{BE(SAT)}$	$I_C=50\text{mA}, I_B=1.25\text{mA}$	0.70		1.05	V
$V_{BE(ON)}$	$V_{CE}=5.0\text{V}, I_C=2.0\text{mA}$	0.55		0.75	V
$h_{FE}$	$V_{CE}=5.0\text{V}, I_C=10\mu\text{A}$	100			
$h_{FE}$	$V_{CE}=5.0\text{V}, I_C=2.0\text{mA}$	380		630	
$h_{FE}$	$V_{CE}=1.0\text{V}, I_C=50\text{mA}$	100			
$f_T$	$V_{CE}=5.0\text{V}, I_C=10\text{mA}, f=100\text{MHz}$	100	250		MHz
$C_c$	$V_{CB}=10\text{V}, I_E=0, f=1.0\text{MHz}$		1.7		pF
$C_e$	$V_{EB}=0.5\text{V}, I_C=0, f=1.0\text{MHz}$		11		pF
NF	$V_{CE}=5.0\text{V}, I_C=200\mu\text{A}, R_S=2.0\text{k}\Omega, f=1.0\text{kHz}, BW=200\text{Hz}$			6.0	dB

R0 (20-June 2016)

# CP388X-BCX70K

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)

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### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)

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### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:  
[www.centrasemi.com/bdspecs](http://www.centrasemi.com/bdspecs)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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**Worldwide Distributors:**  
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